

## IN THE CLAIMS

Claims 1-33 (Canceled).

34 (Currently Amended). A method of making a stencil which may be removably positioned over a semiconductor device for depositing material on the semiconductor before removing the stencil from over the device comprising:

forming a plurality of segmental annular openings in a stencil plate to define a central portion of the plate, a plurality of spokes, and a remainder of said stencil plate, said spokes connecting said central portion to the remainder of said plate between adjacent segmental annular openings; and

depositing material in said openings and under said central portion of said plate.

35 (Previously Presented). The method of claim 34 wherein forming a plurality of segmental annular openings in a stencil plate includes using a stencil plate having a thickness from about 3 to about 10 mils.

36 (Previously Presented). The method of claim 34 including forming said spokes to have a length of about 1 mil.

37 (Previously Presented). The method of claim 34 including forming said central portion in a circular shape.

38 (Previously Presented). The method of claim 34 including forming at least four openings and at least four spokes.

39 (New). The method of claim 34 including maintaining a gap between said stencil and said device.